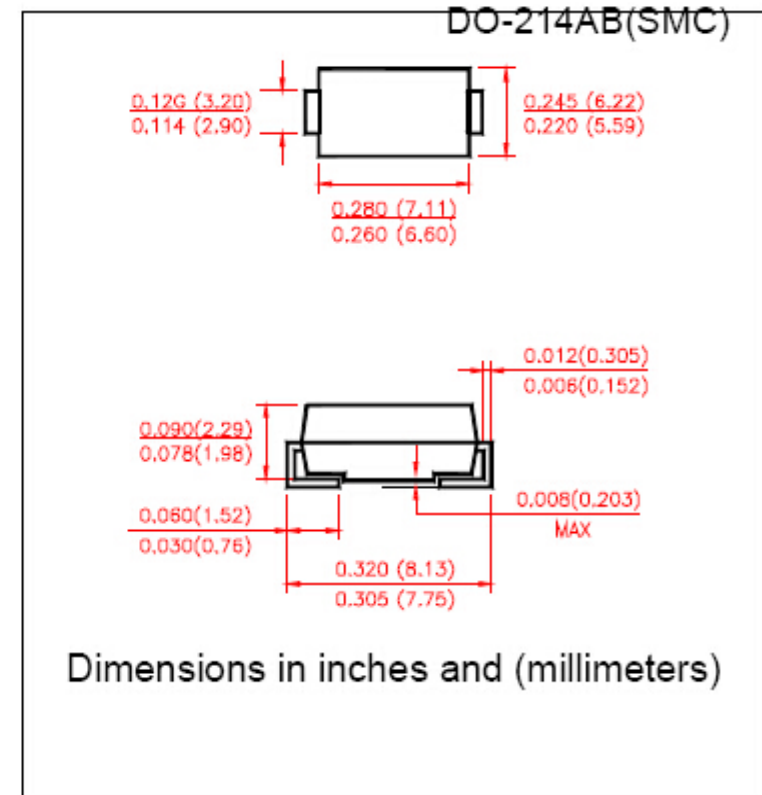


FEATURES

- Low profile surface mount package
- Built-in strain relief
- High switching speed
- Low voltage drop, high efficiency
- For use in low voltage high frequency inverters, Free willing, and polarity protection applications
- Guarding for over voltage protection

MECHANICAL DATA

- Case: Transfer molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Lead: Solder plated, solderable per MIL-STD-750 method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.007 ounce, 0.25 gram



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25°C ambient temperature unless otherwise specified.
- Single phase, half wave, 60Hz, resistive or inductive load.
- For capacitive load derate current by 20%.

| | SYMBOLS | SS32 | SS33 | SS34 | SS35 | SS36 | SS38 | SS39 | SS310 | UNIT |
|---|-----------|------|------|------|------|------|------|------|-------|-------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 20 | 30 | 40 | 50 | 60 | 80 | 90 | 100 | Volts |
| Maximum RMS Voltage | V_{RMS} | 14 | 21 | 28 | 35 | 42 | 56 | 63 | 70 | Volts |
| Maximum DC Blocking Voltage | V_{DC} | 20 | 30 | 40 | 50 | 60 | 80 | 90 | 100 | Volts |

| | | | | | | | | | | |
|---|---------------------------|---------------|----|----|------|---------------|------|----|-----|---------------------------|
| Maximum DC Blocking Voltage | V_{DC} | 20 | 30 | 40 | 50 | 60 | 80 | 90 | 100 | Volts |
| Maximum Average Forward Rectified Current at T_L see figure 1 $T_L=105^\circ\text{C}$ | $I_{(AV)}$ | 3.0 | | | | | | | | Amps |
| Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method) | I_{FSM} | 80 | | | | | | | | Amps |
| Maximum Instantaneous Forward Voltage @ 3.0A(Note1) | V_F | 0.55 | | | 0.75 | | 0.85 | | | Volts |
| Maximum DC Reverse Current at rated DC Blocking Voltage per element | $T_A = 25^\circ\text{C}$ | 0.5 | | | | | | | | mA |
| | $T_A = 100^\circ\text{C}$ | 20.0 | | | | 10.0 | | | | |
| Typical Thermal Resistance (Note 2) | $R_{\theta JA}$ | 55 | | | | | | | | $^\circ\text{C}/\text{W}$ |
| | $R_{\theta JL}$ | 12 | | | | | | | | |
| Operating Junction Temperature | T_J | (-55 to +150) | | | | (-55 to +150) | | | | $^\circ\text{C}$ |
| Storage Temperature Range | T_{STG} | (-55 to +150) | | | | | | | | $^\circ\text{C}$ |

Notes:

1. Pulse test: 300 μs pulse width, 1% duty cycle
2. PCB mounted with 0.55" \times 0.55" (14mm \times 14mm) copper pads